AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

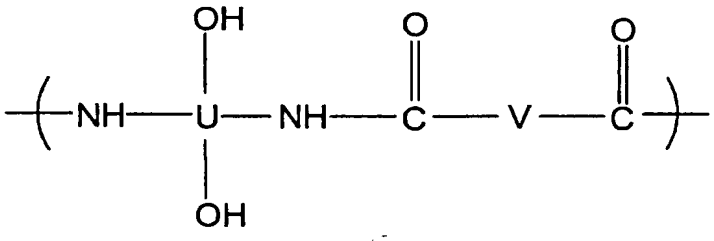
1. (Original) A positive photosensitive resin composition comprising:

(a) alkaline aqueous solution-soluble polyamide having a polyoxazole precursor structure;

(b) an o-quinonediazide compound; and

(c) a latent acid generator which generates acid upon heating.

2. (Original) The positive photosensitive resin composition according to claim 1, wherein the component (a) is a polyamide having a repeating unit represented by the following general formula (I):



(I)

wherein U represents a tetravalent organic group, and V represents a divalent organic group.

3. (Currently amended) The positive photosensitive resin composition according to claim 1 ~~or 2~~, wherein the component (c) is a salt formed of a strong acid and a base.

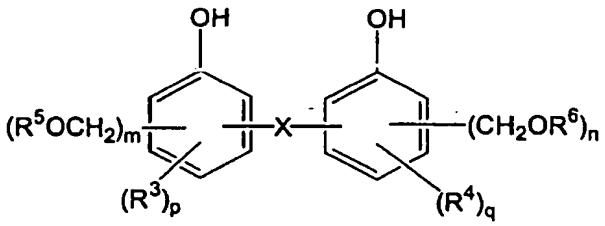
4. (Currently amended) The positive photosensitive resin composition according to claim 1~~any one of claims 1 to 3~~, wherein the component (c) has a decomposition starting temperature of 140 to 250°C.

5. (Currently amended) The positive photosensitive resin composition according to claim 1~~any one of claims 1 to 4~~, wherein the component (c) is a salt of toluenesulfonic acid.

6. (Currently amended) The positive photosensitive resin composition according to claim 1~~any one of claims 1 to 5~~, wherein the component (c) is an iodonium salt.

7. (Currently amended) The positive photosensitive resin composition according to claim 1~~any one of claims 1 to 6~~, further comprising (d) a compound having a phenolic hydroxyl group.

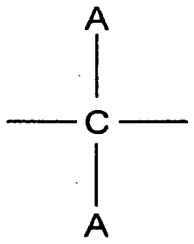
8. (Original) The positive photosensitive resin composition according to claim 7, wherein the component (d) is a compound represented by the following general formula (II):



(II)

wherein X represents a single bond or a divalent organic group, each of R^3 to R^6 independently represents a hydrogen atom or a monovalent organic group, each of m and n is independently an integer of 1 to 3, and each of p and q is independently an integer of 0 to 4.

9. (Original) The positive photosensitive resin composition according to claim 8, wherein the group represented by X in the general formula (II) is a group represented by the following general formula (III):



(III)

wherein each of two A's independently represents a hydrogen atom or an alkyl group having 1 to 10 carbon atoms, and optionally has any one of an oxygen atom and a fluorine atom or both.

10. (Currently amended) The positive photosensitive resin composition according to claim 1~~any one of claims 1 to 9~~, wherein the content of the component (b)

and the content of the component (c) are 5 to 100 parts by weight and 0.1 to 30 parts by weight, respectively, relative to 100 parts by weight of the component (a).

11. (Currently amended) The positive photosensitive resin composition according to claim 7~~any one of claims 7 to 10~~, wherein the content of the component (b), the content of the component (c), and the content of the component (d) are 5 to 100 parts by weight, 0.1 to 30 parts by weight, and 1 to 30 parts by weight, respectively, relative to 100 parts by weight of the component (a).

12. (Currently amended) A method for forming a pattern comprising the steps of:

applying the positive photosensitive resin composition according to claim 1~~any one of claims 1 to 11~~ onto a supporting substrate and drying the composition to obtain a photosensitive resin film;

exposing the photosensitive resin film to a ray of active light having a predetermined pattern; and

developing the exposed photosensitive resin film using an alkaline aqueous solution.

13. (Original) The method according to claim 12, further comprising a step of subjecting the developed photosensitive resin film to a heating treatment.

14. (Original) The method according to claim 13, wherein the heating treatment is a treatment of irradiating the film with a pulse of microwave while changing the frequency thereof.

15. (Currently amended) The method according to claim 13 ~~or 14~~, wherein the heating treatment is conducted at a temperature equal to or lower than 280°C.

16. (Currently amended) An electronic part comprising an electronic device having a layer of pattern obtained by the method for forming a pattern according to claim 12 ~~any one of claims 12 to 15~~,

wherein the device comprises the layer of pattern provided therein as any one of an interlayer insulating layer and a surface protecting film layer or both.

17. (Original) The electronic part according to claim 16 which is MRAM.